Pin Inserter

P350 automatic x-y insertion machine comes with three product-specific insertion heads, each with a rotary insertion finger. Monitors insertion force in real-time and is reportedly capable of inserting 350 pins per min. with a insertion area of 600 x 400 mm max. and 0.02 mm repeatability. Comes with conversion kits for different insertion tools.

Tyco Electronics Automation Group, automation.tycoelectronics.com

Defluxer/Cleaner

Vitrex flux remover reportedly needs no additives, and operates at temperatures between 100º–150ºF (37º–65ºC). Compatible with a range of operation parameters. May be used on multiple-pass cleaning applications.

Aqueous Technologies Corp., aqueoustech.com

Surface Prep Brushes

FybRglass surface preparation brushes are for soldering, painting and epoxying. Can be used for flux removal, edge connector cleaning, trace cleaning for soldering and tarnish removal.

The Eraser Co., eraser.com

Pb-Free X-Ray

VJE X2500 fully automated x-ray inspection system provides high-contrast resolution at high viewing angles. Features integrated motion control, image measurement analysis, a simple 1-2-GO interface and on-screen board representation.

V.J. Electronix Inc., vjelectronix.com

Pick-and-Place Software

Easyplacer version 7.0 expands the component range and increases production speed (up to 5,000 cph) of the CLM9000-PLUS pick-and-place machine. Serial optical inspection enables direct quality control of PCBs. BMS option automatically recognizes check marks and bad marks. Allows complete programming offline, and can distinguish lead-free components.

Essemtec, essemtec.com

Direct Metering Pump

Titan DMS uses progressive cavity metering pump technology to directly meter highly filled, abrasive and shear-sensitive materials from 1 gal. containers to robotic mounted dispense valves. Includes a 1 gal. follower plate, dual air cylinder ram, progressive cavity metering pump, DC brushless servo motor and controls. Does not require additional positive displacement or flow control valves.

Liquid Control Corp., liquidcontrol.com

MEXITRÓNICA

Pb-Free No-Clean Solder

NC368 lead-free, no-clean solder paste is said to achieve bright, smooth and shiny solder joints, and reduce solder defects such as voiding under µBGAs and solder beading by discretes. Reportedly prints at high speeds without slumping, provides consistent stencil release and repeatable print volumes for fine-pitch applications.

AIM, aimsolder.com

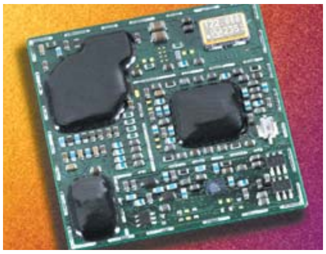
Booth 200

Fine-Pitch Pb-Free Solder

F620 series of lead-free, no-clean solder pastes are said to print through narrow stencil openings. Offers superior wetting and printing, fewer slump-related defects and exceptional lot-to-lot performance. Can be soldered in air and nitrogen on a variety of surfaces.

Heraeus Circuit Materials, heraeus.com

Booth 618



Thermal Interface Film

PowerstrateXtreme is a reworkable phase-change thermal interface material for use between a heatsink and heat-dissipating components. Comes as a freestanding film between two release liners, flows at phase-change temperature and adheres to heatsinks and devices at room temperature.

Henkel Technologies, henkel.com

Booth 510

Label Printer

A1000 applicator, in combination with thermal transfer printers, is for semiautomatic labeling. Integrates into automated production lines.

Cab Technology Inc., cabtechn.com

Booth 703

Stable Pb-Free Paste

M705-GRN360-K lead-free solder paste reportedly exhibits stabile viscosity in storage and use, has good color tone of flux residue and prevents flux residue cracking and solder-balling.

Senju, senju-m.co.jp

Booth 404

Air-Reflow Pb-Free Solder

NC-SMQ230 air reflow, lead-free no-clean solder paste processes in higher temperatures. Is said to provide stable tack life and open time, consistent fine-pitch deposition.

Indium Corp., indium.com

Booth 608

Product SPOTLIGHT

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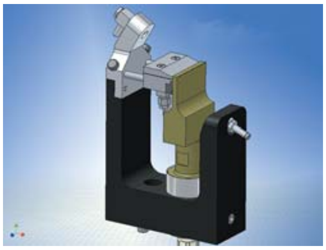
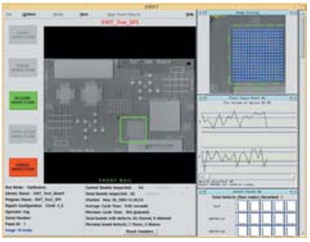


Pb-Free Fluxing

Nozzle-free Ultra-Spray technology with reciprocating motion is for uniform, repeatable application of no-clean, low-solids flux. Provides through-hole penetration for wave soldering.

Ultrasonic Systems Inc., ultraspray.com



Multi-Machine Inspection

SVS application v. 4.7 software manages inspection programs between systems, supporting multiple machines on single or multi-sites. Features improved solder performance on warped flex boards, support for an expanded range of fiducial shapes, presentation improvements and permits re-editing of old programs.

GSI Lumonics Inc., gsilumonics.com

Adhesive Dispenser

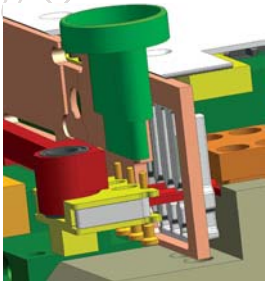
MIXPAC S-50 two-component adhesive dispensing system works with manually operated dispensers and battery-powered handheld dispensers. Can accommodate volumetric ratios of 1:1, 2:1, 4:1, 10:1 and 3:2.

ConProTec Inc., conprotec.com

Automatic Cutter

MMC100 can process round or flat material up to 3.94″ wide x .63″ thick (100 x 16 mm). Maximum force of 600 lbs. for cutting copper wire and cable, silver solder, power cords, latex, belting, etc. Programmable for up to 10 batches and three fixed feed rates; cuts up to 7,200 4″ pieces per hour.

The Eraser Co., eraser.com



Multiple Parts Feeder

Multi-Pick Feeder picks-and-places multiple discrete interconnect pins in a single cycle. Automatically translates 24-mm tape carrying pins from horizontal to vertical and uses a single motion to push multiple pins into a retainer, awaiting pickup by vacuum nozzle. Ejector process can be set up to present two, three or four pins. Feeder mechanism can automatically make pitch adjustments (up to 1-2 mm) as pins are transferred from tape to retainer.

Autosplice, autosplice.com

Tabletop AOI

The compact YTV-1000 provides automated off-line inspection of solder and lead defects, component presence and position, correct part, polarity and through-hole parts. Effective for pre/post-reflow or final assembly inspection. Said to have low false failure rate, features remote programming and real-time SPC monitoring.

YESTech, yestechinc.com

Automated Gold Wire Bonder

Model 8000 gold ball-and-stitch thermosonic wire bonder is ideal for complex multichip applications, high I/O count devices and gold ball bumping for flip chip. Incorporates a 300 x 150 mm x-y range linear motor-actuated positioner. The 72 in^2 (45,000 mm^2) work area accommodates dual handling systems. Said to achieve accurate targeting and wire placement of better than 5 µm.

Palomar Technologies, bonders.com

Pick-and-Place Machine

FX-1 places 25,000 components per hour and uses linear motors for quieter operation. Its single-piece frame reduces manufacturing time while reportedly increasing machine ridgidity, accuracy and durability. Dual head on a single x beam design.

Juki Automation Systems, jas-smt.com

Wafer Sort and Final Memory Tester

Versatest Model V5400?s algorithmic pattern generator (APG) and tester-per-site (TPS) architecture provide configuration flexibility and up to four times higher throughput for wafer sort and final memory testing. Tests standard and stacked memory modules such as flash, DRAM and SRAM while offering up to 4,608 channels and 144 independent test sites.

Agilent Technologies Inc., agilent.com

Send your product releases
to Robin Norvell at
rnorvell@upmediagroup.com.